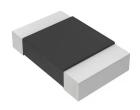


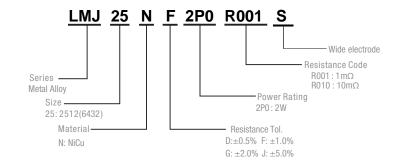


### Description

- Proprietary processing technique produces extremely low resistance values
- Very low inductance
- Low thermal EMF
- Metallic Material

### Part Numbering System





Parameter	Standard
Power Rating	2 W
Resistance Value	1~10mΩ
Operating Temperature Range	-55 to +170°C
Component Temperature Coefficient (TCR)	± 50 ppm/°C
Maximum Working Voltage (V)	(P x R) <sup>1/2</sup>
Rating Current (A)	(P / R) <sup>1/2</sup>

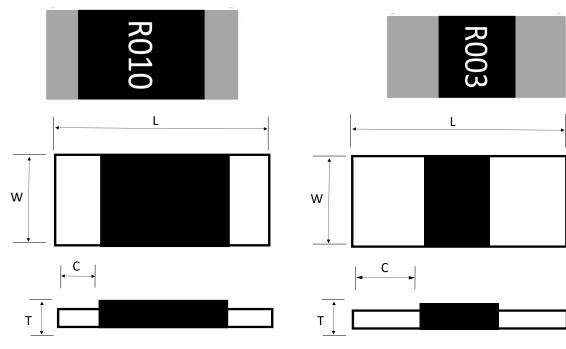
P=Power Rating; R=Resistance Value

### **Standard Electrical Specifications**

Туре	Rating Power at 70℃	T.C.R. (ppm/℃)	Resistance Range(mΩ ±0.5% (D) ±1.0% (F) ±2.0% (G) ±5.0% (J)	Meterial	Electrode	Operating Temperature(℃)
LMJ25	2W	50	1-10	R001-R010:NiCu	R001-R004:Wide R002-R010:Narrow	-55~+170°C

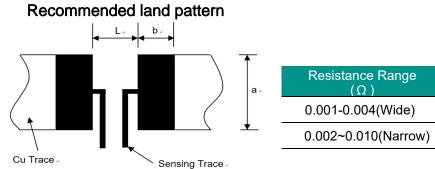


### Construction



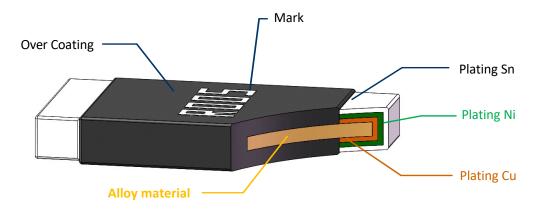
Unit: Millimeters

Туре	Power	L	W	С	t	
		0.410.0	2.2+0.2	0.95±0.25 (Narrow)		
LMJ 25	2W	6.4±0.2	3.2±0.2	2.1±0.25 (Wide)	0.9±0.2	



	Unit: Millimeters								
P	Resistance Range ( Ω )	а	b	L					
	0.001-0.004(Wide)	4.0±0.1	3.1±0.1	1.3±0.1					
	0.002~0.010(Narrow)	4.0±0.1	2.1±0.1	4.1±0.1					

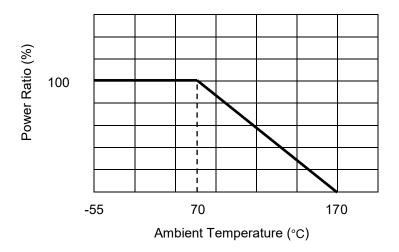
Product structure diagram



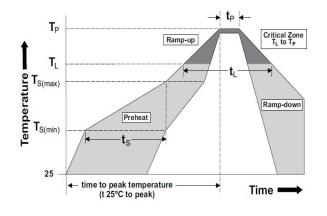


## **Power Derating Curve**

For resistors operated in ambient temperatures 70°C, power rating shall be derated inaccording with the curve below:



# **Recommended Solder Curve**



Reflow Cond	lition	Pb – Free assembly		
Kenow Conc		FD – Hee assembly		
Pre heat	- Temperature Min (Ts(min))	150°C		
	- Temperature Max (Ts(max))	200°C		
	- Time (Min to Max) (ts)	60 – 120 secs		
	Average ramp up rate uidus Temp (TL) to peak	5°C/second max		
TS(I	max) to TL - Ramp-up Rate	5°C/second max		
Reflow	- Temperature (TL) (Liquidus)	217°C		
	- Time(tL)	60 – 150 seconds		
I	Peak Temperature (TP)	260°C		
Time within 5	°C of actual peak Temperature (tp)	20 – 40 seconds		
	Ramp-down Rate	5°C/second max		
Time 2	5°C to peak Temperature (TP)	8 minutes Max.		
	Wave Soldering	260°C, 10 seconds max.		
	Hand Soldering	350°C, 5 seconds max.		

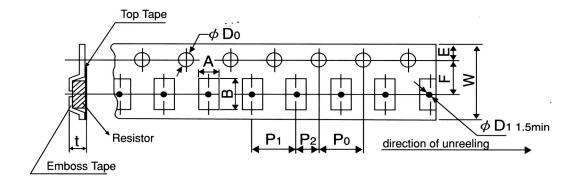


# **Product Characteristics**

Item	Test condition/ Methods	Limited	Standard
Resistance	Measuring resistance value at room temperature 25℃±5℃	Refer to Spec	IEC60115-1 4.5
Temperature coefficient of resistance	$TCR = (R-R_0)/R_0(T2-T1)X \ 10^6 \\ T1 \ T2 \\ R_0: resistance of room temperature \\ R: resistance of 125 °C \\ T1: Room temperature \\ T2: Temperature at 125 °C \\ \end{array}$	Refer to Spec	MIL-STD-202 Method 304
Short time Overload	Apply overload for 5 seconds and measure the resistance change rate after standing for 24 hours. 5 times the rated power for 5 seconds	≤±0.5%	MIL-R-26E
Resistance to Soldering Heat	260℃±5℃ time: 10sec±1sec	≤±0.5%	MIL-STD-202 Method 210
Temperature Cycling	-55℃ (30min)/+125℃(30min), 1000 cycles	≤±0.5%	MIL-STD-202 Method107G
Low temperature Storage	-55 °C for 1000hours, No power	≤±0.5%	MIL-STD-26E
High Temperature Storage	125°C for 1000hours, No power	≤±1%	IEC6011501-4.25
Bias Humidity	+85℃,85% RH,10%bias, 1000hours	≤±0.5%	MIL-STD-202 Method103
Joint Strength of Solder Solder Solder Solder Solder Solder Solder the center of the test plate, measure its resistance variance rate under load		≤±0.5%	JIS-C5201
Solderability	Solderability 245±5°C, 2±0.5sec		IEC60115-1-4.17 JIS-C5201-4.17
Operational life	70℃±2℃, 1000 hours, at rated power 1.5 hours "ON", 0.5 hours "OFF"	≤±1%	MIL-STD-202 Method 108

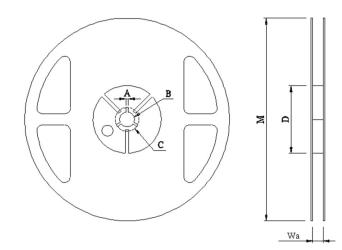


### Tapping & Package



Туре	Pack	<b>A</b> ±0.2		<b>D0</b> +0.5-0	<b>E</b> ±0.1	<b>F</b> ±0.05	<b>P0</b> ±0.1	<b>P1</b> ±0.1	<b>P2</b> ±0.1	<b>W</b> ±0.2		<b>T</b> ±0.15
2512	Emboss	3.60	6.90	1.50	1.75	5.50	4.00	4.00	2.00	12.00	1.50	1.20

### **Reel Specification**



Туре	Α	В	С	D	М	w
2512	2.00±0.5	13.50±0.5	21.00±0.5	80.00±1.0	178.00±2.0	13.80±0.5

## Packaging

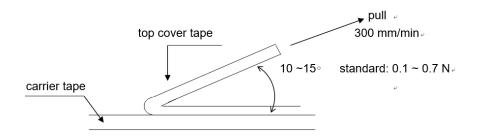
Quantity: 4, 000pcs

8mm wide tape on 178mm(7 inch) diameter reel -specification EIA Standard 481.



# Peel strength of upper belt

Stripping speed: 300 mm / min; The peel force is between 0.1N and 0.7n.



# Storage conditions & shelf life

It can be stored for 2 years under closed conditions with temperature of 5  $^\circ$  C  $\sim$  35  $^\circ$  C and relative humidity of 40  $\sim$  75

Please avoid the following harsh environment during storage to avoid affecting the product performance and solder connectivity: the places with corrosive gases such as sea breeze, Cl2, H2S, NH3, SO2 and NO2 shall be stored without direct sunlight.

# Precautions for product use

When measuring the resistance value before welding, a special resistance meter with high precision shall be used. When measuring, a 4-wire probe or fixture must be used. 4. When measuring parts with a wire measuring needle, the 4 measuring needles must indeed contact the parts.

Avoid damaging the protective layer during manual welding or clamping with tweezers.

When the PCB is divided or fixed on the support, be careful to avoid excessive bending causing mechanical stress to the resistor.

It shall be used within the rated power range within the specification, especially when the power exceeds the rated value, which may affect the reliability of the product